

PCN # 1708A

DATE: October 20, 2017

EXPECTED PCN SHIP DATE: October 20, 2017



Quality Assurance
160 Rio Robles
San Jose, CA 95134

www.maximintegrated.com

PROCESS CHANGE NOTICE
 PRODUCT CHANGE NOTICE

MAXIM INTEGRATED HEREBY ISSUES NOTIFICATION OF CHANGE
THAT MAY AFFECT THE FOLLOWING CATEGORIES:

DESIGN WAFER FAB ASSEMBLY TEST ELEC/MECH SPECS

AFFECTED PRODUCT:

Ordering P/N: (See PN listing XLS in PCN ZIP file)

CHANGE FROM: Conductive die attach Epoxy ABLESTIK
8290 Drop-on

CHANGE TO: Conductive Die Attach Film (DAF) CDAF500
applied on back of wafer

JUSTIFICATION: Improving device quality/reliability by reducing the possibility of shorting internal pins due to excessive drop-on epoxy, by changing the process to use wafer back-side Die Attach Film (DAF).

There is no impact to the form/fit/function of the devices.

TRACEABILITY: Maxim Integrated maintains full traceability by device marking, packaging labels and shipment documents.

Maxim Integrated's Change Notification System is designed to keep our customer base apprised of major product, manufacturing, or facility improvements.

Nasser Ali Chaouche

Nasser AliChaouche / PCN Coordinator

For further information, please contact either of the people listed below.

Contact your local Maxim Integrated Company Representative or Nasser AliChaouche, PCN Coordinator
408-601-5660 / pcn.coordinator@maximintegrated.com